

- B¹
concl'd
- c) drying the slip at temperatures from room temperature through 300°C; and
 - d) alitizing or aluminizing the slip layer to form an adhesive layer, whereby the method is controlled so that the adhesion layer comprises a structure having a grain size less than 75μm and a cavity proportion from 0 through 40%.--

Page 3, please amend the paragraph starting at line 23 to read as follows:

B²

--In a preferred development of the method, the final step of alitizing or aluminizing the slip layer is implemented at a temperature between 800 and 1200°C and a duration of 1 through 12 hours. The aluminizing serves the purpose of diffusion joining and compacting the layer and is implemented in a standard method such as, for example, in the powder pack method upon introduction of Al. The Al diffuses into the layer and into the basic material of the component part.--

IN THE CLAIMS:

Please amend claim 1 to read as follows:

~~--1. (Amended) Method for manufacturing an adhesion layer for a heat insulating layer that is applied onto a component part, the method comprising the steps:~~

- ~~B³
Sub
C1~~
- ~~a) producing a slip by mixing powders containing at least one of the elements Cr, Ni or CE with a binding agent;~~
 - ~~b) applying the slip onto the component part;~~
 - ~~c) drying the slip at temperatures from room temperature through 300°C; and~~
 - ~~d) alitizing the slip layer to form the adhesion layer, whereby the method is controlled so that the adhesion layer comprises a structure having a grain size less than 75μm and a cavity proportion from 0 through 40%.--~~